ON Semiconductor



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20601

Generic Copy

Issue Date: 09-Dec-2014

TITLE: Manufacturing of Large body Clip QFN products at Amkor Technology Philippines

PROPOSED FIRST SHIP DATE: 16-Mar-2015

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Manufacturing Assembly and Test

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or Rob Prestoza < rob.prestoza@onsemi.com >

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Nicky Siu <<u>nicky.siu@onsemi.com</u>>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This is a Final Product/Process Change Notification to alert customers of the qualification of Amkor Technology Philippines to assemble and test products in Large body Clip QFN package listed in this notification. Amkor Technology Philippines will provide additional capacity to supplement ON Semiconductor's current Assembly and Test in Seremban, Malaysia and Carmona, Philippines, respectively.

Upon implementation of the change on this FPCN, the affected parts may be sourced from any previously qualified Manufacturing locations.

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RELIABILITY DATA SUMMARY:

Qual Vehicle: NCP5369MNR2G

Test	Conditions	Interval	<u>Result</u>
HTOL	Ta=125°C, with bias	504hrs	0/80
HTSL	Ta=150°C	1008hrs	0/240
Preconditioning	MSL 3@260°C, 3 X IR at 260°C		
TC+PC	Ta= -55/150°C, air to air	500cyc	0/240
HAST+PC	Ta=130°C, RH=85%, Pressure=18.8Psig, 80% rated or 100V max	96hrs	0/240
UHAST+PC	Ta=130°C, RH=85%, Pressure=18.8Psig	96hrs	0/240
RSH	Ta=260°C Immersion		0/90
Solderability	Steam Aging=8hrs, Ta=245°C		0/45
DPA	AEC-Q101-004, Post HTSL 1008hrs, TC500cycs & HAST96hrs		0/6
WPS	Mil-Std-750 Method 2037, Post TC500cycs		0/15
	& HAST96hrs		
For HS-FET			
HTRB	Ta=150°C, Vds=80% Rated Voltage	504hrs	0/240
HTGB	Ta=150°C, Vgs=100% Rated Voltage	504hrs	0/240
Preconditioning	MSL 3@260°C, 3 X IR at 260°C	004113	0/240
TC+PC	Ta= $-55/150^{\circ}$ C, air to air	500cyc	0/240
HAST+PC	Ta=130°C, RH=85%, Pressure=18.8Psig,	96hrs	0/240
	80% rated or 100V max	oomo	0/210
UHAST+PC	Ta=130°C, RH=85%, Pressure=18.8Psig	96hrs	0/240
IOL+PC	Ta=25°C, Delta Tj=100°C Ton/off = 2mins	7500cyc	0/240
For LS-FET			
HTRB	Ta=150°C, Vds=80% Rated Voltage	504hrs	0/240
HTGB	Ta=150°C, Vgs=100% Rated Voltage	504hrs	0/240
Preconditioning	MSL 3@260°C, 3 X IR at 260°C	004113	0/240
TC+PC	Ta= $-55/150^{\circ}$ C, air to air	500cyc	0/240
H3TRB+PC	Ta=85°C, 85% RH, 80% rated or 100V max	504hrs	0/240
UHAST+PC	Ta=130°C, RH=85%, Pressure=18.8Psig	96hrs	0/240
IOL+PC	Ta=25°C, Delta Tj=100°C Ton/off = 2mins	7500cyc	0/240
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ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

CHANGED PART IDENTIFICATION:

Devices assembled by Amkor Technology Philippines will include the character "2" as Assembly Plant identifier in the Trace Code information.

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List of affected General Parts:

NCP5369MNR2G NCP5369MNTWG NCP5369NMNTXG NCP81081MNR2G NCP81081MNTWG NCP5338MNR2G